

Title (en)

SYSTEM FOR COOLING AN INTEGRATED CIRCUIT WITHIN A COMPUTING DEVICE

Title (de)

SYSTEM ZUR KÜHLUNG EINER INTEGRIERTEN SCHALTUNG IN EINER BERECHNUNGSVORRICHTUNG

Title (fr)

SYSTÈME PERMETTANT DE REFROIDIR UN CIRCUIT INTÉGRÉ DANS UN DISPOSITIF INFORMATIQUE

Publication

EP 2973689 A1 20160120 (EN)

Application

EP 14774761 A 20140219

Priority

- US 201361786300 P 20130314
- US 2014017184 W 20140219

Abstract (en)

[origin: WO2014158481A1] One variation of a system for cooling an electrical component within a computing device - including a digital display - includes: an internal heatsink thermally coupled to the integrated circuit and defining a fluid passage including a first end and a second end; a heat exchange layer arranged across a viewing surface of the digital display, including a transparent material, and defining a fluid channel extending across a portion of the digital display, the fluid channel including a fluid inlet coupled to the first end of the fluid passage and a fluid outlet coupled to the second end of the fluid passage; a transparent fluid; and a displacement device configured to circulate the transparent fluid between the internal heatsink and the fluid channel.

IPC 8 full level

G02F 1/1333 (2006.01); **G06F 1/20** (2006.01); **G06F 3/01** (2006.01); **H01L 23/473** (2006.01); **H05K 7/20** (2006.01)

CPC (source: EP)

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Designated extension state (EPC)

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